



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Wu

Docket No.: TI-33005

Serial No.: 09/997,972

Art Unit: 2812

Filed: 11/29/01

Examiner: Lattin, C

Title: Method For Manufacturing And Structure Of Semiconductor Device With Polysilicon Definition Structure

AMENDMENT UNDER 37 CFR 1.111

September 19, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

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TECHNOLOGY CENTER 2800

<b>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</b>	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on <u>9-19-03</u> as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
<u>Karen Vertz</u> Karen Vertz	<u>9-19-03</u> Date

In response to the Office Action, dated 06/20/2003, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.